# imall

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# 50 mA, Wide Input Range, Voltage Regulator

The NCP4640 is a CMOS 50 mA linear voltage regulator with high input voltage and ultra-low supply current. It incorporates multiple protection features such as peak current limit, short circuit current limit and thermal shutdown to ensure a very robust device.

A high maximum input voltage tolerance of 50 V and a wide temperature range make the NCP4640 suitable for a variety of demanding applications.

### Features

- Operating Input Voltage Range: 4 V to 36 V
- Output Voltage Range: 2.0 to 12.0 V (0.1 steps)
- $\pm 2\%$  Output Voltage Accuracy
- Output Current: min 50 mA ( $V_{IN} = 8 \text{ V}, V_{OUT} = 5 \text{ V}$ )
- Line Regulation: 0.05%/V
- Peak Current Limit Circuit
- Short Current Limit Circuit
- Thermal Shutdown Circuit
- Available in SOT-89-5 and SOIC6-TL Package
- These are Pb–Free Devices

# **Typical Applications**

- Power source for home appliances
- Power source for car audio equipment, navigation system
- Power source for notebooks, digital TVs, cordless phones and private LAN systems
- Power source for office equipment machines such as copiers, printers, facsimiles, scanners, projectors, etc.

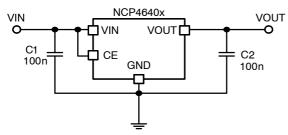


Figure 1. Typical Application Schematic



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http://onsemi.com

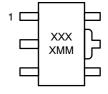
MARKING DIAGRAMS







SOT-89 5 CASE 528AB



XXXX = Specific Device Code MM = Date Code

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 15 of this data sheet.

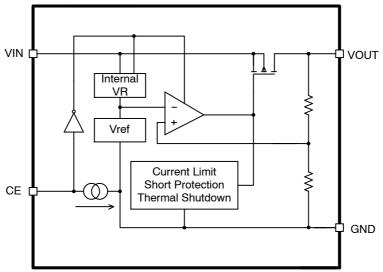


Figure 2. Simplified Schematic Block Diagram

Pin No. SOT89	Pin No. SOIC6-TL	Pin Name	Description
5	6	VIN	Input pin
2	2	GND	Ground pin, all ground pins must be connected together when it is mounted on board
4	4	GND	Ground pin, all ground pins must be connected together when it is mounted on board
_	5	GND	Ground pin, all ground pins must be connected together when it is mounted on board
3	3	CE	Chip enable pin ("H" active)
1	1	VOUT	Output pin

#### **PIN FUNCTION DESCRIPTION**

#### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Input Voltage	V <sub>IN</sub>	–0.3 to 50	V
Peak Input Voltage (Note 1)	V <sub>IN</sub>	60	V
Output Voltage	Vout	$-0.3$ to Vin + 0.3 $\leq 50$	V
Chip Enable Input	VCE	$-0.3$ to Vin + 0.3 $\leq 50$	V
Output Current	I <sub>OUT</sub>	150	mA
Power Dissipation SOT-89	PD	900	mW
Power Dissipation SOIC6-TL		1700	
Junction Temperature	TJ	-40 to 150	°C
Storage Temperature	T <sub>STG</sub>	-55 to 125	°C
ESD Capability, Human Body Model (Note 2)	ESD <sub>HBM</sub>	2000	V
ESD Capability, Machine Model (Note 2)	ESD <sub>MM</sub>	200	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability. 1. Duration time = 200 ms

Duration time = 200 ms
 This device series incorporates ESD protection and is tested by the following methods: ESD Human Body Model tested per AEC-Q100-002 (EIA/JESD22-A114) ESD Machine Model tested per AEC-Q100-003 (EIA/JESD22-A115) Latchup Current Maximum Rating tested per JEDEC standard: JESD78.

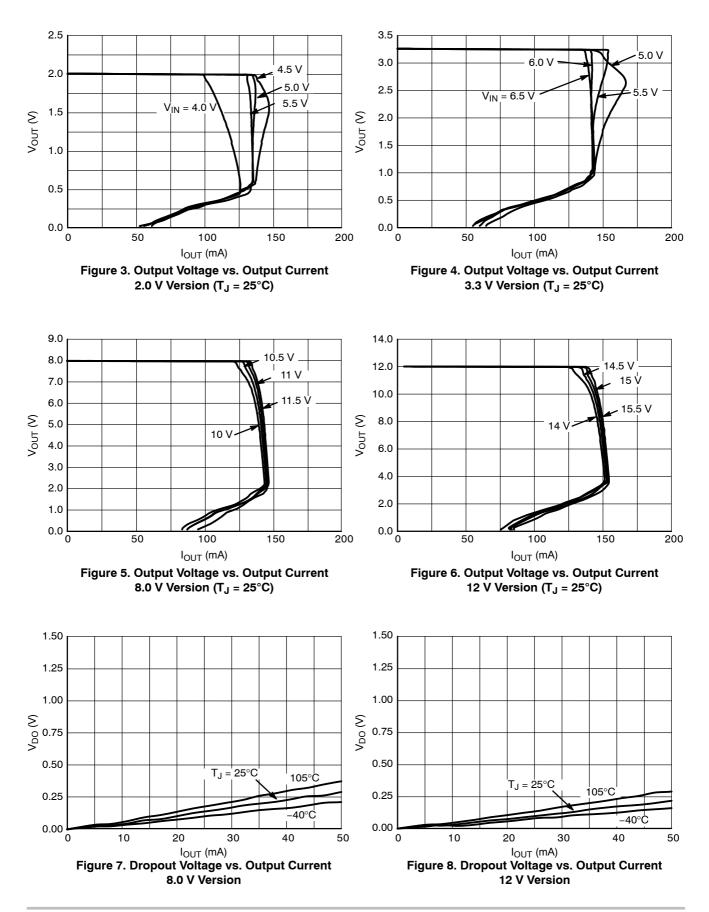
### THERMAL CHARACTERISTICS

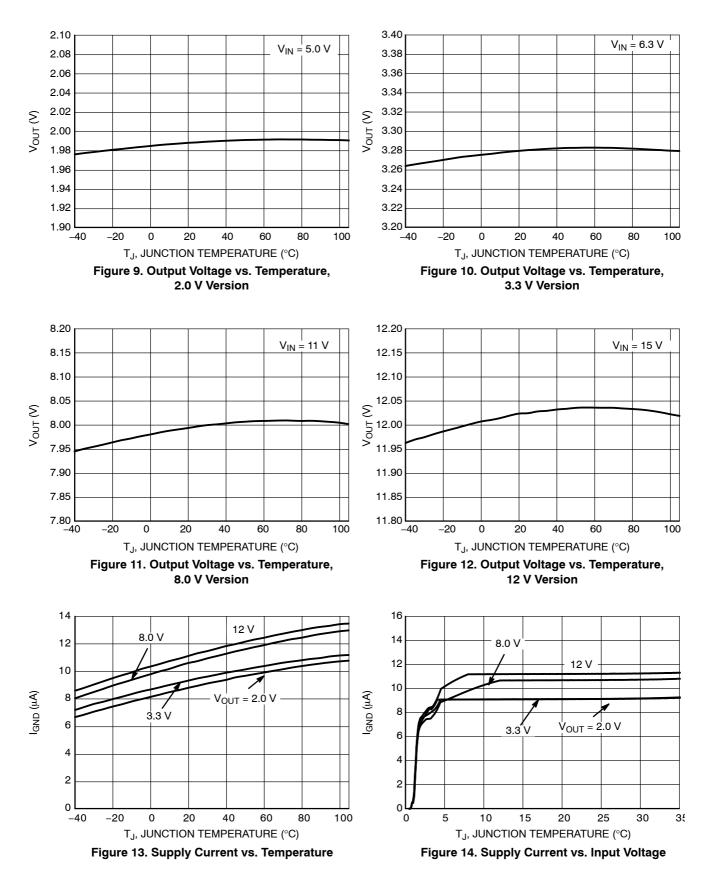
Rating	Symbol	Value	Unit
Thermal Characteristics, SOT-89 Thermal Resistance, Junction-to-Air	$R_{ hetaJA}$	111	°C/W
Thermal Characteristics, SOIC6-TL Thermal Resistance, Junction-to-Air	$R_{\theta JA}$	59	°C/W

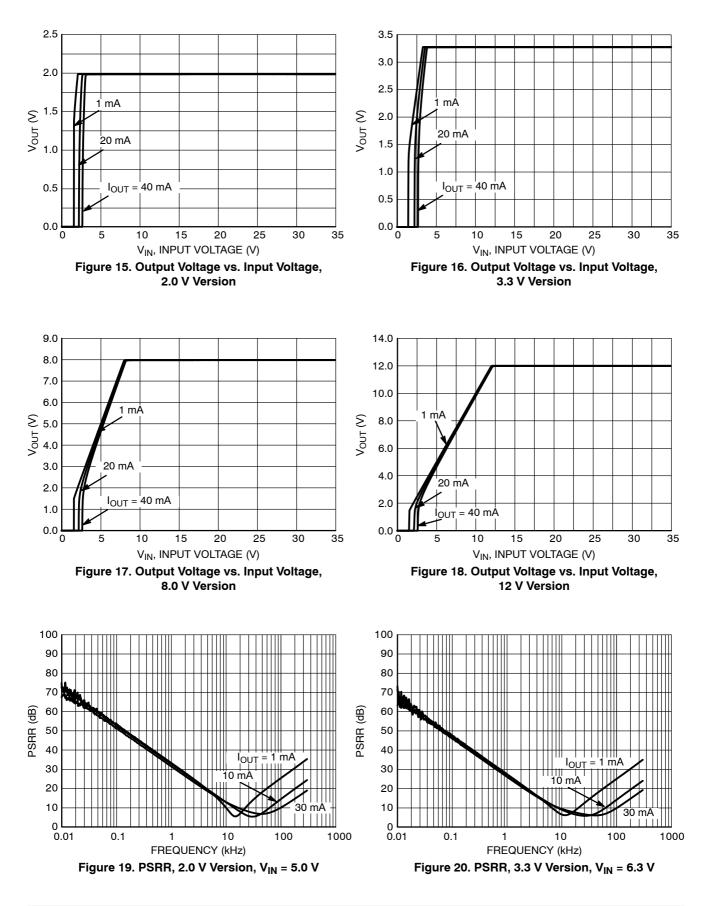
# **ELECTRICAL CHARACTERISTICS** $T_A = 25^{\circ}C$

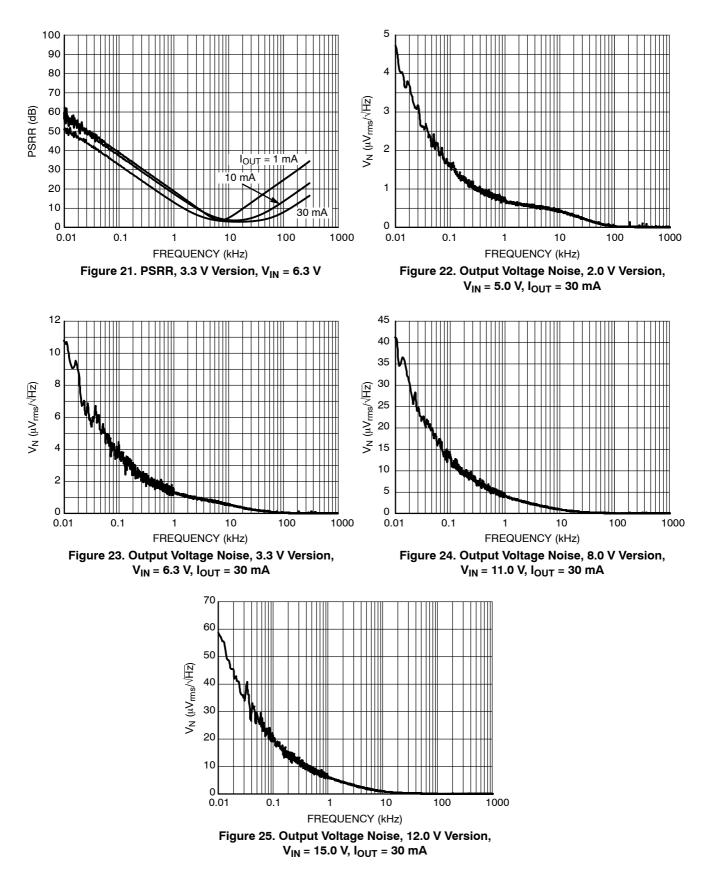
Parameter	Test Conditions		Symbol	Min	Тур	Max	Unit
Operating Input Voltage			Vin	4		36	V
Output Voltage	V <sub>IN</sub> = Vout + 3 V, I <sub>OUT</sub> = 1 mA		Vout	x0.98		x1.02	V
Output Voltage Temp. Coefficient	$V_{IN}$ = Vout + 3 V, $I_{OUT}$ = 1 mA, $T_A$ = –40 to $105^\circ C$				±100		ppm/°C
Line Regulation	$V_{IN} = V_{OUT} + 1.5 V$ to 36 V, $I_{OUT} = 1 \text{ mA}$		Line <sub>Reg</sub>		0.05	0.20	%/V
Load Regulation	$V_{IN} = V_{OUT} + 3 V,$	$2.0~\text{V} \leq \text{V}_{\text{OUT}} < 5.0~\text{V}$	Load <sub>Reg</sub>		10	25	mV
	IOUT = 1 mA to 40 mA	$5.0 \text{ V} \le \text{V}_{OUT} < 12.0 \text{ V}$			20	35	
Dropout Voltage	I <sub>OUT</sub> = 20 mA	$2.0~\text{V} \leq \text{V}_{\text{OUT}} < 3.7~\text{V}$	Vdo			(Note 3)	V
		$3.7 \text{ V} \le \text{V}_{\text{OUT}} < 4.0 \text{ V}$	1		0.35	0.60	
		$4.0 \text{ V} \le \text{V}_{OUT} < 5.0 \text{ V}$	1		0.25	0.40	
		$5.0 \text{ V} \le \text{V}_{\text{OUT}} < 12.0 \text{ V}$			0.20	0.35	
Output Current	V <sub>IN</sub> = Vout + 3 V		Іоит	50			mA
Short Current Limit	V <sub>OUT</sub> = 0 V		I <sub>SC</sub>		50		mA
Quiescent Current	V <sub>IN</sub> = Vout + 3 V, Iout = 0 mA		lq		9	20	μA
Standby Current	V <sub>IN</sub> = 36 V, V <sub>CE</sub> = 0 V		Istb		0.1	1	μΑ
CE Pin Threshold Voltage	CE Input \	/oltage "H"	VCEH	1.5		V <sub>IN</sub>	V
	CE Input V	Voltage "L"	VCEL	0		0.3	
Thermal Shutdown Temperature			T <sub>SD</sub>		150		°C
Thermal Shutdown Release Temperature			T <sub>SR</sub>		125		°C
Power Supply Rejection Ratio	$\label{eq:VIN} \begin{array}{l} \text{Vin} = 5.0 \text{ V},  \text{V}_{\text{OUT}} = 2.0 \text{ V},  \Delta \text{V}_{\text{IN} \text{ PK}-\text{PK}} = 0.2 \text{ V}, \\ \text{I}_{\text{OUT}} = 30 \text{ mA},  \text{f} = 1   \text{Hz} \end{array}$		PSRR		30		dB
Output Noise Voltage	$V_{OUT}$ = 2.0 V, $I_{OUT}$ = 30 mA, f = 10 Hz to 100 kHz		VN		80		$\mu V_{rms}$

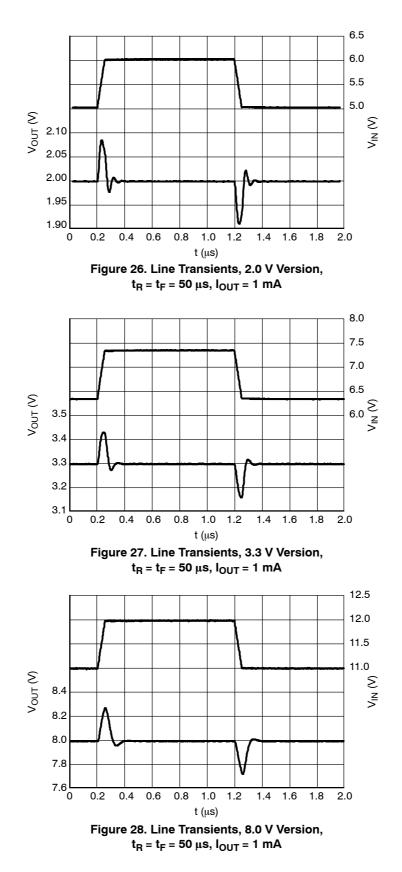
3. Dropout voltage for 2.0 V  $\leq$  V<sub>OUT</sub> < 3.7 V can be computed by this formula: V<sub>DO</sub> = 4 V - V<sub>OUTSET</sub>



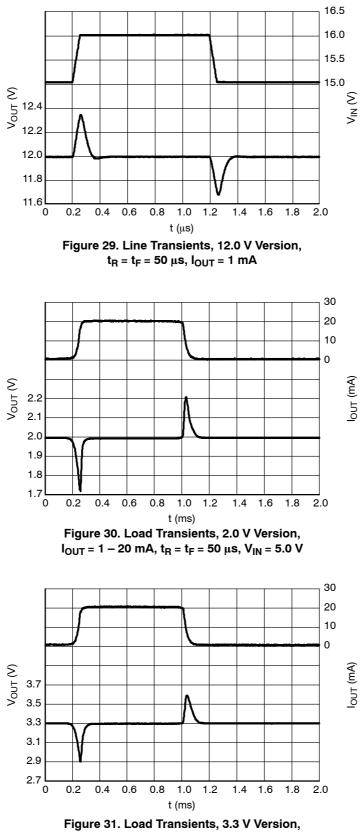




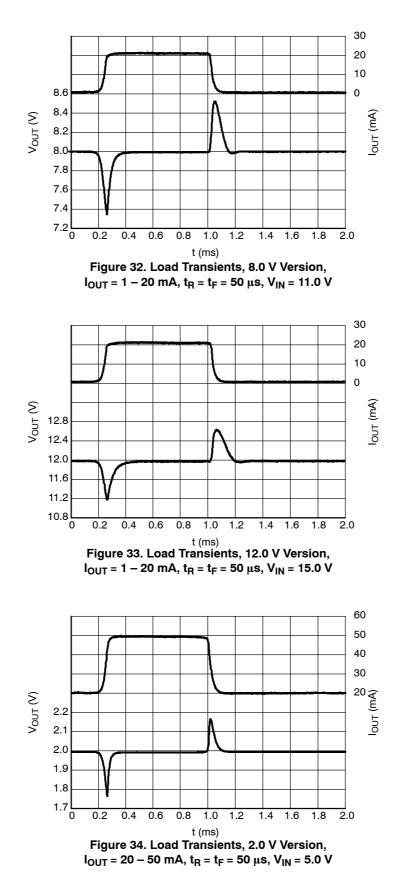


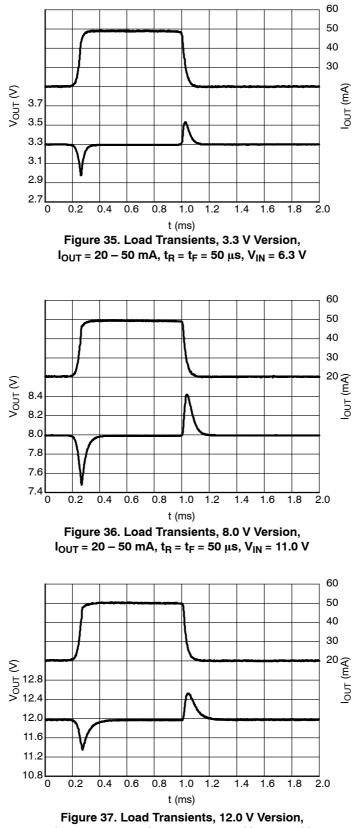


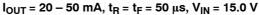


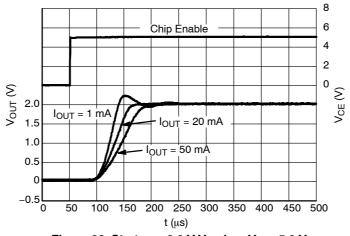


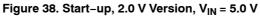
 $I_{OUT} = 1 - 20 \text{ mA}, t_{R} = t_{F} = 50 \ \mu\text{s}, V_{IN} = 6.3 \text{ V}$ 











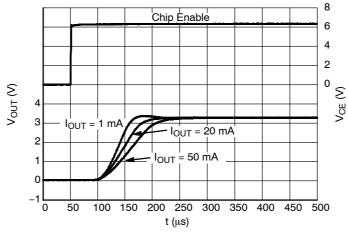
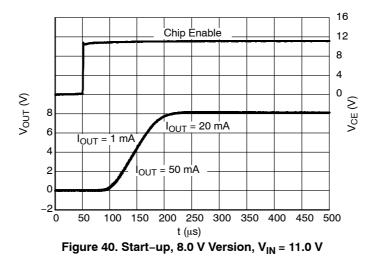


Figure 39. Start–up, 3.3 V Version,  $V_{IN}$  = 6.3 V



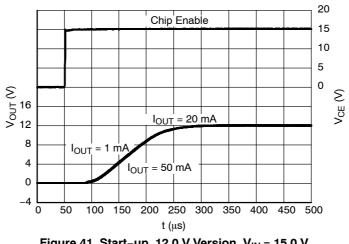


Figure 41. Start-up, 12.0 V Version, V<sub>IN</sub> = 15.0 V

#### APPLICATION INFORMATION

A typical application circuit for NCP4640 series is shown in Figure 42.

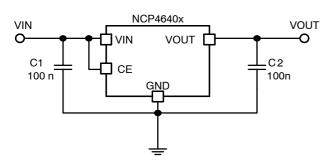


Figure 42. Typical Application Schematic

#### Input Decoupling Capacitor (C1)

The device is stable without any input capacitance, but if input line is long and has high impedance or if more stable operation is needed, input capacitor C1 should be connected as close as possible to the IC. Recommended range of input capacitor value is 100 nF to 10  $\mu$ F.

#### **Output Decoupling Capacitor (C2)**

The NCP4641 can work stable without output capacitor, but if faster response and higher stability reserve is needed, output capacitor should be connected as close as possible to the device. Recommended range of output capacitance is 100 nF to 10  $\mu$ F. Larger values of output capacitance and lower ESR improves dynamic parameters.

#### **Enable Operation**

The enable pin CE may be used for turning the regulator on and off. The device is activated when high level is connected to CE pin. Do not keep CE pin not connected or between VCEH and VCEL voltage levels. Otherwise output voltage would be unstable or indefinite and unexpected would flow internally.

#### Thermal

As a power across the IC increase, it might become necessary to provide some thermal relief. The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and also the ambient temperature affect the rate of temperature increase for the part. When the device has good thermal conductivity through the PCB the junction temperature will be relatively low in high power dissipation applications.

The IC includes internal thermal shutdown circuit that stops operation of regulator, if junction temperature is higher than 150°C. After that, when junction temperature decreases below 125°C, the operation of voltage regulator would restart. While high power dissipation condition is, the regulator starts and stops repeatedly and protects itself against overheating.

#### PCB layout

Pins number 2 and 4 of SOT89–5 package and pins number 2, 4 and 5 of SOIC6–TL must be wired to the GND plane while it is mounted on board. Make VIN and GND lines sufficient. If their impedance is high, noise pickup or unstable operation may result. Connect capacitors C1 and C2 as close as possible to the IC, and make wiring as short as possible.

Device	Nominal Output Voltage	Description	Marking	Package	Shipping <sup>†</sup>
NCP4640H020T1G	2.0 V	Enable High	N020	SOT89–5 (Pb–Free)	1000 / Tape & Reel
NCP4640H030T1G	3.0 V	Enable High	N030	SOT89–5 (Pb–Free)	1000 / Tape & Reel
NCP4640H033T1G	3.3 V	Enable High	N033	SOT89–5 (Pb–Free)	1000 / Tape & Reel
NCP4640H080T1G	8.0 V	Enable High	N080	SOT89–5 (Pb–Free)	1000 / Tape & Reel
NCP4640H120T1G	12.0 V	Enable High	N120	SOT89–5 (Pb–Free)	1000 / Tape & Reel

#### ORDERING INFORMATION

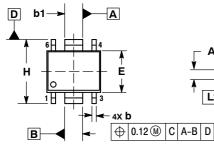
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

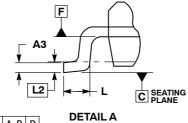
\*To order other package and voltage variants, please contact your ON Semiconductor sales representative.

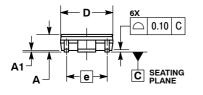
#### PACKAGE DIMENSIONS

#### SOIC6 (HSOP6) CASE 751BR-01

ISSUE O

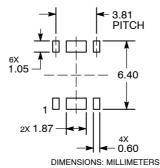








#### RECOMMENDED **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

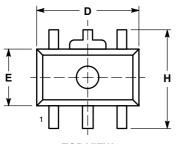
- NOTES:
  DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS
  DIMENSION b AND b1 DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWAQBLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
  DATUMS A AND B ARE DETERMINED AT DATUM F.
  DATUMS A AND B ARE DETERMINED AT DATUM F.
  DATUMS A AND B ARE DETERMINED AT DATUM F.
  DATUMS A AND B ARE DETERMINED AT DATUM F.
  MAI IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
  - POINT ON THE PACKAGE BODY.

entre				
	MILLIMETERS			
DIM	MIN	MAX		
Α	1.45	1.85		
A1	0.05	0.25		
A3	0.19	0.30		
b	0.30	0.50		
b1	1.57	1.77		
D	4.72	5.32		
Е	3.70 4.10			
е	3.81 BSC			
н	5.70	6.30		
Ĺ	0.40	0.60		
L2	0.25 BSC			

#### PACKAGE DIMENSIONS

SOT-89, 5 LEAD

CASE 528AB-01 **ISSUE O** 



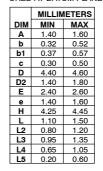




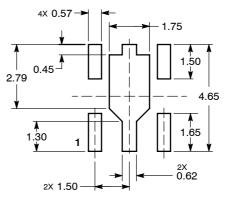
b. <⊢b L2 L5 <-D2→ **BOTTOM VIEW** 

NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. 2
- LEAD THICKNESS INCLUDES LEAD FINISH.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD
- FLASH, PROTRUSIONS, OR GATE BURRS. DIMENSIONS L, L2, L3, L4, L5, AND H ARE MEAS-5 URED AT DATUM PLANE C.



RECOMMENDED **MOUNTING FOOTPRINT\*** 



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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